

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPT008N06NM5LF	**Issued**	24. February 2022
MA#	MA005708880		
Package	PG-HSOF-8-1	**Weight***	776.22 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	6.557	0.84	0.84	8447	8447
chip_2	inorganic material	silicon	7440-21-3	0.390	0.05	0.05	503	503
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		163	
	non noble metal	iron	7439-89-6	0.421	0.05		542	
	non noble metal	copper	7440-50-8	420.040	54.12	54.19	541133	541838
wire	noble metal	gold	7440-57-5	0.065	0.01		83	
	non noble metal	aluminium	7429-90-5	18.320	2.36	2.37	23602	23685
encapsulation	inorganic material	zincoxide	1314-13-2	3.175	0.41		4090	
	miscellaneous	miscellaneous	-	12.698	1.64		16359	
	plastics	epoxy resin	-	47.619	6.13		61347	
	inorganic material	silicondioxide	60676-86-0	253.969	32.72	40.90	327186	408982
leadfinish	non noble metal	tin	7440-31-5	6.479	0.83	0.83	8347	8347
plating	inorganic material	phosphorus	7723-14-0	0.001			2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	678	680
solder	non noble metal	tin	7440-31-5	0.114	0.01		147	
	noble metal	silver	7440-22-4	0.143	0.02		184	
	non noble metal	lead	7439-92-1	5.455	0.70	0.73	7027	7358
glue	plastics	Polyimide	26023-21-2	0.124	0.02	0.02	160	160
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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